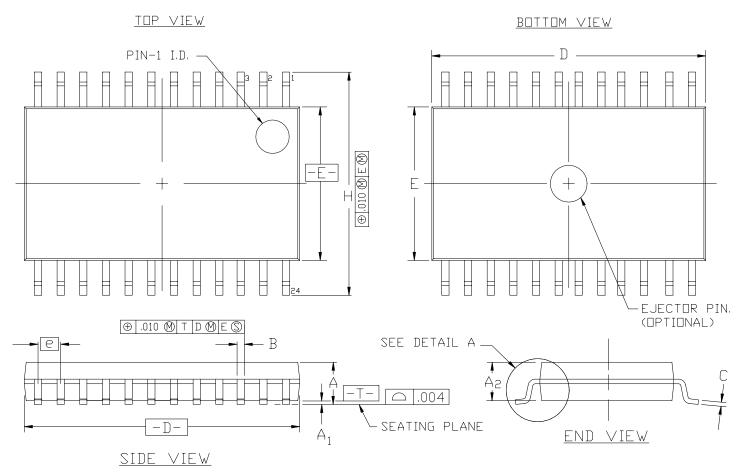
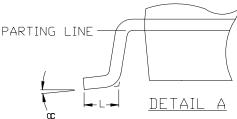
TSOP (VO24) Package



S M B	INCHES		
_ L	MIN.	NDM.	MAX.
Α			.0472
A_1	.002		.006
Aa	.031		.041
В	.0075		.0118
С	.0035		.0078
D	.303	.307	.311
E	.169	.173	.177
9	.0256 BSC		
Н	.252 BSC		
L	.0197	.0236	.0295
œ	0 *	5*	8*



NOTES:

- 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982.
- 2. DIMENSION "D" DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED .006" PER SIDE.
- 3. DIMENSION "E" DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED .010" PER SIDE.
- 4. LEAD FINISH: SOLDER PLATE
- 5. CONFORMS TO JEDEC MS-153-AD

24-LEAD TSOP (VO24)

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